

SKiiP® 2

4-pack - integrated intelligent Power System

Power section

SKiiP 592GH170-4D

Features

- SKiiP technology inside
- CAL diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiiP® 2 System)
- IEC 60068-1 (climate) 40/125/56
- UL recognized file no. E63532

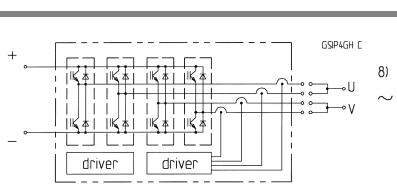
1) with assembly of suitable MKP capacitor per terminal (SEMIKRON type is recommended)

8) AC connection busbars must be connected by the user; copper busbars available on request

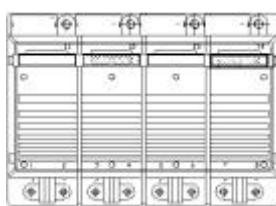
Absolute Maximum Ratings		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	Values		Units
IGBT				
V_{CES}		1700		V
$V_{CC}^1)$	Operating DC link voltage	1200		V
V_{GES}		± 20		V
I_C	$T_s = 25 \text{ (70)}^\circ\text{C}$	500 (375)		A
Inverse diode				
$I_F = -I_C$	$T_s = 25 \text{ (70)}^\circ\text{C}$	500 (375)		A
I_{FSM}	$T_j = 150^\circ\text{C}$, $t_p = 10 \text{ ms}$; sin.	4320		A
I^2t (Diode)	Diode, $T_j = 150^\circ\text{C}$, 10 ms	93		kA²s
$T_{j1} (T_{stg})$		- 40 (-25) ... + 150 (125)		°C
V_{isol}	AC, 1 min. (mainterminals to heat sink)	4000		V

Characteristics		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	min.	typ.	max.
IGBT				
V_{CEsat}	$I_C = 400 \text{ A}$, $T_j = 25 \text{ (125)}^\circ\text{C}$	3,3 (4,3)	3,9	V
V_{CEO}	$T_j = 25 \text{ (125)}^\circ\text{C}$	1,7 (2)	2 (2,3)	V
r_{CE}	$T_j = 25 \text{ (125)}^\circ\text{C}$	4 (5,9)	4,8 (6,6)	mΩ
I_{CES}	$V_{GE} = 0 \text{ V}$, $V_{CE} = V_{CES}$, $T_j = 25 \text{ (125)}^\circ\text{C}$	(30)	2	mA
$E_{on} + E_{off}$	$I_C = 400 \text{ A}$, $V_{CC} = 900 \text{ V}$ $T_j = 125^\circ\text{C}$, $V_{CC} = 1200 \text{ V}$		345	mJ
			509	mJ
$R_{CC' + EE'}$	terminal chip, $T_j = 125^\circ\text{C}$	0,25		mΩ
L_{CE}	top, bottom	7,5		nH
C_{CHC}	per phase, AC-side	1,6		nF
Inverse diode				
$V_F = V_{EC}$	$I_F = 400 \text{ A}$, $T_j = 25 \text{ (125)}^\circ\text{C}$	2,3 (2,1)	2,9	V
V_{TO}	$T_j = 25 \text{ (125)}^\circ\text{C}$	1,3 (1)	1,6 (1,3)	V
r_T	$T_j = 25 \text{ (125)}^\circ\text{C}$	2,5 (2,8)	3,2 (3,5)	mΩ
E_{rr}	$I_C = 400 \text{ A}$, $V_{CC} = 900 \text{ V}$ $T_j = 125^\circ\text{C}$, $V_{CC} = 1200 \text{ V}$	42		mJ
		50		mJ
Mechanical data				
M_{dc}	DC terminals, SI Units	6	8	Nm
M_{ac}	AC terminals, SI Units	13	15	Nm
w	SKiiP® 2 System w/o heat sink	3,5		kg
w	heat sink	8,5		kg
Thermal characteristics (P16 heat sink; 275 m³/h); "r" reference to temperature sensor				
$R_{th(j-s)I}$	per IGBT		0,04	K/W
$R_{th(j-s)D}$	per diode		0,133	K/W
$R_{th(s-a)}$	per module		0,033	K/W
Z_{th}	R_i (mK/W) (max. values)		$\tau_{ai}(s)$	
	1 2 3 4	1 2 3 4		
$Z_{th(j-r)I}$	4 31 5 0	1 0,13 0,001 1		
$Z_{th(j-r)D}$	15 103 16 0	1 0,13 0,001 1		
$Z_{th(r-a)}$	1,6 22 7 2,4	494 165 20 0,03		

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Case S 5



SKiiP® 2

4-pack - integrated intelligent Power System

4-pack integrated gate driver

SKiiP 592GH170-4D

Gate driver features

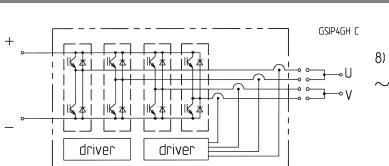
- Two separate and independent "GB"-type driver
- CMOS compatible input
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- U-option is integrated on left driver, (DC terminals at bottom; refer to case drawing)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protected against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option)
- IEC 60068-1 (climate) 25/85/56

Absolute Maximum Ratings		$T_a = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions	Values		Units
V_{S1}	stabilized 15 V power supply	18		V
V_{S2}	unstabilized 24 V power supply	30		V
V_{iH}	input signal voltage (high)	15 + 0,3		V
$\frac{dv}{dt}$	secondary to primary side	75		$\text{kV}/\mu\text{s}$
V_{isolIO}	input / output (AC, r.m.s., 2s)	4000		Vac
V_{isol12}	output 1 / output 2 (AC, r.m.s., 2s)	1500		Vac
f_{sw}	switching frequency	10		kHz
f_{out}	output frequency for $I=I_C \sin.$	1		kHz
$T_{op} (T_{stg})$	operating / storage temperature	- 40 ... + 85		°C

Characteristics $(T_a = 25^\circ\text{C})$				
Symbol	Conditions	min.	typ.	max.
V_{S1}	supply voltage stabilized	14,4	15	15,6
V_{S2}	supply voltage non stabilized	20	24	30
I_{S1}	$V_{S1} = 15 \text{ V}$	$210+440*f/f_{\text{max}}+1,2*(I_{AC}/A)$		
I_{S2}	$V_{S2} = 24 \text{ V}$	$160+310*f/f_{\text{max}}+0,85*(I_{AC}/A)$		
V_{iT+}	input threshold voltage (High)	12,3		
V_{iT-}	input threshold voltage (Low)	4,6		
R_{IN}	input resistance	10		
$t_{d(on)}IO$	input-output turn-on propagation time	1,5		
$t_{d(off)}IO$	input-output turn-off propagation time	1,4		
$t_{pERRRESET}$	error memory reset time	9		
t_{TD}	top / bottom switch : interlock time	3,3		
$I_{analogOUT}$	8 V corresponds to max. current of 15 V supply voltage (available when supplied with 24 V)	500		
$I_{Vs1outmax}$	output current at pin 12/14	50		
I_{A0max}	logic low output voltage	5		
V_{O1}	logic high output voltage	0,6		
V_{OH}		30		
I_{TRIPSC}	over current trip level ($I_{analog OUT} = 10 \text{ V}$)	625		
I_{TRIPLG}	ground fault protection	A		
T_{tp}	over temperature protection	110		
U_{DCTRIP}	trip level of U_{DC} -protection ($U_{analog OUT} = 9 \text{ V}$); (option)	1200		

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